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JC979 U.S. PTO
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03/01/02

March 1, 2002

The Commissioner of Patents
& Trademarks
U.S. PATENT & TRADEMARK OFFICE
Box Patent Application
Washington, D.C. 20231

Re: Enclosed Patent Application
Our Ref. No. 1527.003

Dear Sir:

Please find enclosed a new patent application entitled "Polishing Pad for Use in Chemical-Mechanical Planarization of Semiconductor Wafers and Method of Making Same", by the inventors/applicants: Richard Cooper, Angie Mroczek Petroski, David Perry, and Paul Fathauer.

The enclosed application consists of 26 pages of specification, claims, and abstract, and 5 sheets of informal drawing.

The enclosed application is being filed without a Declaration and Power of Attorney, and without the filing fee.

Respectfully,

HAMMAN & BENN



Milton S. Gerstein
Reg. No. 27,891

Enclosures

CERTIFICATE OF EXPRESS MAILING

EXPRESS MAIL CERTIFICATE NUMBER: EV 036583095US

The undersigned hereby certifies that the enclosed application entitled "Polishing Pad for Use in Chemical-Mechanical Planarization of Semiconductor Wafers and Method of Making Same", by the inventors/applicants: Richard Cooper, Angie Mroczek Petroski, David Perry, and Paul Fathauer, is being mailed to the U.S. Patent & Trademark Office, via U.S. Postal Service Express Mail Service, certificate number EL 036583095US, on this the 1st day of March, 2002. The enclosed application consists of 26pages of specification and abstract, and 5 sheets of drawing.

By: 

Milton S. Gerstein
Reg. No. 27891